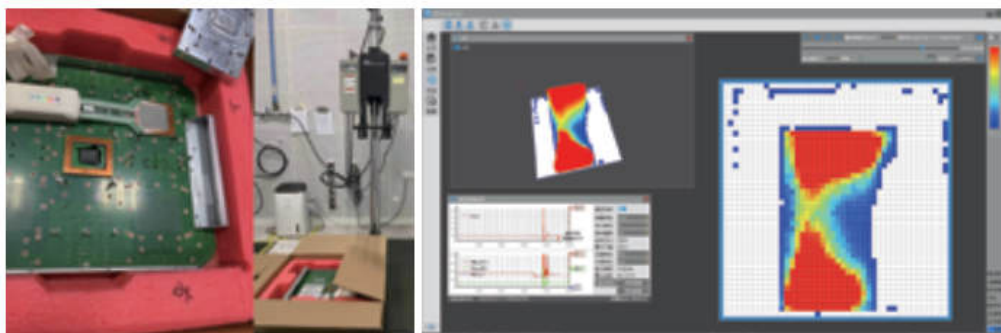


3C CHIP DROP PRESSURE DISTRIBUTION TEST PROGRAM

PROJECT INTRODUCTION

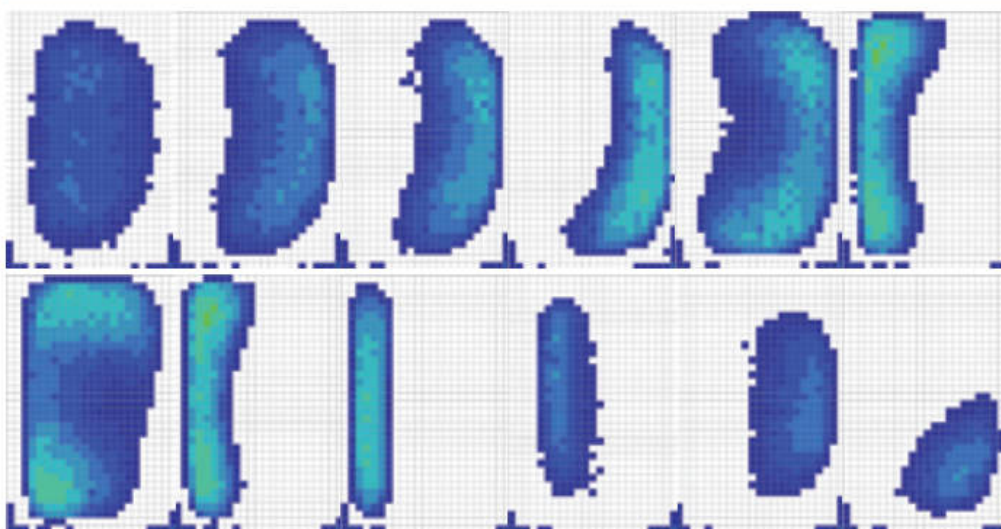
As one of the components of the chip, the heat sink needs to be assembled with the chip as a complete set. During transportation and installation, uncontrollable factors can cause the chip to fall instantly, resulting in damage to the chip caused by the heat sink, thus affecting the normal use of the chip.



MEASUREMENT PROCESS

The thin-film sensors are installed in the chip package, and after connecting the equipment, the complete set of routers is packed and dropped through the dropping machine for different heights and different speeds.

MEASUREMENT RESULT



Compared to traditional pressure sensitive paper measurement, the picture is clearer and the high frequency acquisition expands the measurement direction. The data from drop measurement verifies the feasibility of the mounting solution and improves the integrity of the chip during transportation and installation.

USE

Product Structure Optimization
Product design validation

ADVANTAGES

Provide data
Adjustment of the chip
protection layer
Material and position

EQUIPMENT: D3

High-speed type
Distributed Pressure
Measurement System
DPM-HS



MODEL	CN5051
Sensing area	57mm *57mm
No. of sensing points	1936, 44rows*44columns
Point density	59.2points/cm ²
Pressure ranges	10/50/150/250psi